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Declarations under Rule 4.17:

— as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))

[Continued on next page]

(54) Title: HIGH TEMPERATURE CHUCK AND METHOD OF USING SAME

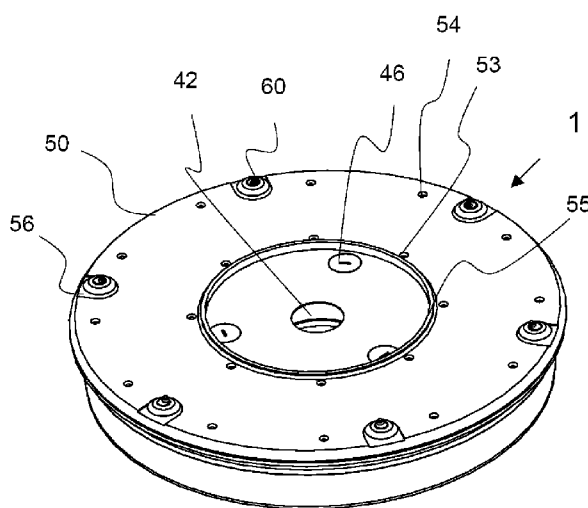


Fig. 1

(57) Abstract: Improved resistance to temperature-related degradation or deformation in a wafer-supporting chuck is provided by at least one shielding member that physically and/or thermally shields chuck components from effects of elevated temperature processing fluids.



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- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*
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